

IN THE CLAIMS:

Please amend the claims of the International Application as shown below. The status of the claims after amendment will be as follows.

Claims 1 - 8 (cancelled)

9. A wave soldering tank comprising a soldering tank body for housing molten solder, a solder feed chamber disposed within the soldering tank body and having an inlet disposed below the level of molten solder and an outlet disposed above the level of molten solder in the soldering tank body, and a multiple-blade screw-type pump disposed in the inlet so as to draw molten solder into the solder feed chamber through the inlet and discharge molten solder through the outlet.

10. (new) A wave soldering tank as claimed in claim 9, wherein the pump includes an impeller comprising a rotatable hub and a plurality of helical blades secured to the hub at equal intervals in the circumferential direction of the hub.

11. (new) A wave soldering tank as claimed in claim 10, wherein each of the blades overlaps an adjoining one of the blades when the blades are viewed in the axial direction of the impeller.

12. (new) A wave soldering tank as claimed in claim 11 wherein the impeller comprises four helical blades provided at equal intervals in the circumferential direction of the hub, each blade extending around the hub by at least 120° between first and second ends of the blade.

13. (new) A wave soldering tank as claimed in claim 10 wherein each of the blades is sloped by at most 45° with respect to a plane perpendicular to a rotational axis of the hub.

14. (new) A wave soldering tank as claimed in claim 9 wherein the solder feed chamber comprises a partition which divides the interior of the soldering tank body into an upper and lower portion, the inlet comprises an opening formed in the partition, and the pump includes an impeller and a cylindrical casing disposed in the inlet and surrounding the impeller, the impeller being rotatably disposed in the casing so as to transport molten solder in an axial direction of the casing.

15. (new) A wave soldering tank as claimed in claim 14 wherein the solder feed chamber includes a duct which extends upwards from the partition and a nozzle disposed at an upper end of the duct and extending above the surface of molten solder in the soldering tank body.

16. (new) A wave soldering tank as claimed in claim 14 wherein a lower end of the impeller extends 5 - 10 mm below a

lower end of the casing.

17. (new) A wave soldering tank as claimed in claim 14 wherein a clearance between the casing and the impeller is 0.1 - 1 mm.